



(19) **United States**

(12) **Patent Application Publication**
Takayama et al.

(10) **Pub. No.: US 2003/0162312 A1**
(43) **Pub. Date: Aug. 28, 2003**

(54) **VEHICLE, DISPLAY DEVICE AND
MANUFACTURING METHOD FOR A
SEMICONDUCTOR DEVICE**

(30) **Foreign Application Priority Data**

Nov. 30, 2001 (JP) 2001-367412

Publication Classification

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(51) **Int. Cl.⁷** **H01L 21/00**; H01L 27/15; H01L 31/12; H01L 33/00; H01L 51/40; H04B 1/034
(52) **U.S. Cl.** **438/22**; 438/26; 438/99; 257/79; 257/81; 455/99

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(57) **ABSTRACT**

To provide a semiconductor device in which a layer to be peeled is attached to a base having a curved surface, and a method of manufacturing the same, and more particularly, a display having a curved surface, and more specifically a light-emitting device having a light emitting element attached to a base with a curved surface. A layer to be peeled, which contains a light emitting element furnished to a substrate using a laminate of a first material layer which is a metallic layer or nitride layer, and a second material layer which is an oxide layer, is transferred onto a film, and then the film and the layer to be peeled are curved, to thereby produce a display having a curved surface.

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(21) Appl. No.: **10/303,080**

(22) Filed: **Nov. 25, 2002**

